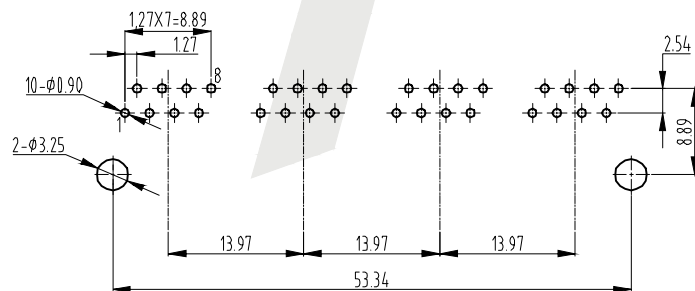
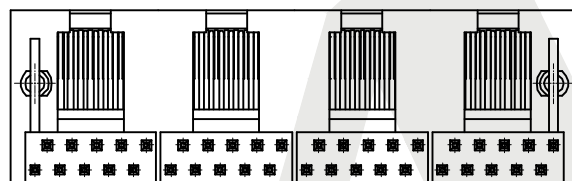
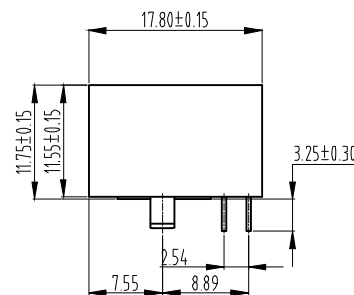
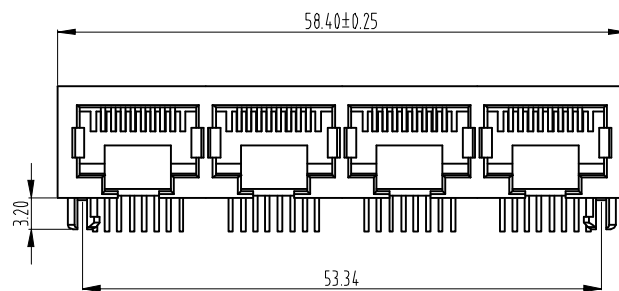


HSF



ROHS



PCB LAYOUT/TOP VIEW

NOTES:

MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING $1\mu\sim50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE ELECTRICAL
1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTION PRB-SOLDER: 1 LB MIN REVRONMENTAL
1. STORAGE: -40°C TO 85°C
2. OPERATION: 0°C TO 70°C

Order code:

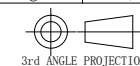
ATRJ5623 - 10P - 8C - X - A - C

① ② ③ ④ ⑤ ⑥

- ① SERIES NO: ⑤ Shield
② NUMBER OF POSITIONS (10P, 8P, 6P, 4P) A: W/O Shield
③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C) B: Half Shield
④ Contact Plating C: Shield W/Eml
D: Shield W/O Eml
G0: Gold flash ⑥ Ports
G1: 3U" Gold A: 1X1P
G2: 5U" Gold B: 1X2P
G3: 10U" Gold C: 1X4P
G4: 15U" Gold D: 1X5P
G5: 30U" Gold E: 1X6P
SN: Tin F: 1X8P

Unless Otherwise specified tolerance
X. ± 0.35 X.XX: ± 0.20
X.X: ± 0.25 X.XXX: ± 0.15

SCALE: As Shown UNIT: mm
DRAW Wu Feng Rong DATE 22/03/2018
CHECK BobYang DATE 22/03/2018



ANTENK ELECTRONICS CO., LTD
Http://www.antenk.com
E-mail: sales@antenk.com

TITLE: RJ45 Jack side entry, Full Plastic with bump

DRAWING NO: ATRJ5623-10P8C-X-A-C

PRODUCT NO: ATRJ5623-10P8C-X-A-C

REV

DESCRIPTION

DATE

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